

IN THE CLAIMS

Please amend the claims in accordance with the following rewritten claims in clean form. Applicant includes herewith an Attachment for Claim Amendments showing a marked up version of each amended claim.

1. (Amended) A circuit board comprising:
a substrate;
a first component mounted on said substrate by a solder connection;
a second component mounted on said substrate with an anisotropic conductive film interposed therebetween; and
a band-shaped region on the substrate which includes said second component, and which does not include said first component.

2. (Amended) A circuit board according to claim 1, wherein said first component further comprises one of a passive element and a mechanism component, while said second component further comprises a semiconductor device.

3. (Amended) A circuit board according to claim 1, wherein said band-shaped region is wider than a pressing surface of a thermocompression bonding head which is employed in mounting said second component to said substrate.

4. (Amended) A circuit board according to claim 1, wherein an alignment mark is provided on said substrate outside said band-shaped region.

5. (Amended) A circuit board according to claim 1, wherein the solder connection further comprises a reflow solder connection.

6. (Amended) A circuit board according to claim 1, wherein a plurality of first components are disposed on said substrate, and said band-shaped region is located between the plurality of first components.

7. (Amended) A circuit board according to claim 6, wherein said second component further comprises one of a power source IC and a power source LSI.

8. (Amended) A circuit board according to claim 1, wherein said band-shaped region extends from one end of said substrate to another end of said substrate.

9. (Amended) A circuit board according to claim 1, wherein said band-shaped region extends rectilinearly along said substrate.

10. (Amended) A circuit board according to claim 1, further comprising wiring patterns formed on said substrate in said band-shaped region.

11. (Amended) A circuit board according to claim 1, further comprising a dummy electrode formed at a position on said substrate corresponding to said second component.

12. (Amended) A display device comprising said circuit board of claim 1, and display means connected to said circuit board.

13. (Amended) A display device according to claim 12, wherein said display means further comprises a liquid crystal device which includes substrates, and said circuit board is connected to said substrates.

14. (Amended) A display device according to claim 12, wherein a plurality of first components are disposed on said substrate, said band-shaped region is located between the plurality of first components, and said second component further comprises one of a power source IC, a power source LSI, a liquid crystal driving IC and a liquid crystal driving LSI.

15. (Amended) A method of manufacturing a circuit board comprising:
the step of mounting a first component on a substrate by solder connection;
the step of arranging an anisotropic conductive film on a predetermined position of the substrate;
the step of arranging a second component on the anisotropic conductive film;
and
the step of thermocompression-bonding the second component to said substrate with said anisotropic conductive film held therebetween;

wherein said step of arranging said anisotropic conductive film on the predetermined position of said substrate is performed after said step of mounting the first component on said substrate by the solder connection.

16. (Amended) A method of manufacturing a circuit board according to claim 15, wherein said step of mounting said first component on said substrate by the solder connection includes a reflow treatment.

Please add the following new claims.

17. (New) A circuit board comprising:
a substrate including a band-shaped region;
a first component soldered to said substrate outside of said band-shaped region;
a second component mounted to said substrate inside of said band-shaped region; and
an anisotropic conductive film disposed between said second component and said substrate.

18. (New) The circuit board of claim 17 wherein a plurality of first components are soldered to said substrate on opposite sides of said band-shaped region.

19. (new) The circuit board of claim 17 wherein said band-shaped region extends rectilinearly along said substrate from one end of said substrate to another end of said substrate.

20. (new) The circuit board of claim 17 wherein said band-shaped region has a width which is wider than a width of a pressing surface of a thermocompression bonding head used to mount said second component to said substrate.

REMARKS

The purpose of this preliminary amendment is to clarify the translation and add new claims. Favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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